

AMENDMENT TO CLAIMS

Please amend the claims on the amended sheets accompanying the IPER filed concurrently herewith. The listing of claims below will replace all prior versions and listings of claims in the application:

1. (Original) A superconductive composite tape (1), comprising a substrate (2) and a layer (5) made of superconductive material, said superconductive material layer (5) comprising a plurality of superconductive filaments (11), which are substantially parallel to one another and to a longitudinal axis (A) of the tape and are spaced out from one another; the tape being characterized in that it comprises a coating (30) made of a conductive coating material, the filaments (11) being embedded in the coating (30); and in that each filament (11) is delimited by a pair of side walls (15) provided with resistive barriers (25).

2. (Original) The tape according to Claim 1, characterized in that the resistive barriers (25) are defined by respective portions (26) of the side walls (15) in which the superconductive material has a structure modified with respect to the body of the superconductive material layer (5).

3. (Currently Amended) The tape according to Claim 1 ~~or 2~~, characterized in that the filaments (11) are separated from one another by grooves (14) formed through said superconductive material layer (5) throughout the whole thickness of said superconductive material layer (5).

4. (Original) The tape according to Claim 3, characterized in that the grooves (14) are interrupted by transverse bridges (17) for connection between adjacent filaments (11).

5. (Currently Amended) The tape according to Claim 3 ~~or Claim 4~~, characterized in that the grooves (14) extend in depth up to the substrate (2).

6. (Currently Amended) The tape according to ~~any one of Claims 3 to 5~~, characterized in that it comprises at least one buffer layer (4), interposed between the substrate (2) and the superconductive material layer (5), the grooves (14) extending through the superconductive material layer (5) and through the buffer layer (4) up to the substrate (2).

7. (Currently Amended) The tape according to ~~any one of the preceding Claims 1~~, characterized in that the coating material is a metal material.

8. (Currently Amended) The tape according to ~~any one of the preceding Claims 1~~, characterized in that the coating (30) fills the grooves (14) and coats the filaments (11).

9. (Currently Amended) The tape according to ~~any one of the preceding Claims 1~~, characterized in that it is wound on itself around said axis (A) to form a thread (33) in which said filaments (11) are substantially parallel to said axis (A).

10. (Currently Amended) The tape according to ~~any one of the preceding Claims 1~~, characterized in that it is twisted on itself along said axis (A) to form a tress-like thread (33), in which the filaments (11) are substantially spirally wound with respect to one another.

11. (Currently Amended) The tape according to ~~any one of the preceding Claims 1~~, characterized in that the filaments (11) are connected to one another by transverse bridges (17) made of superconductive material.

12. (Original) A method of fabrication of superconductive composite tapes, comprising a step of providing a superconductive composite tape (1) having a superconductive material layer (5) positioned on a substrate (2), and a step of forming in the superconductive material layer (5) a plurality of superconductive filaments (11) delimited by respective pair of side walls (15), the filaments (15) being substantially parallel to one another and to a longitudinal axis (A) of the tape and being spaced out from one another; the method being characterized by further comprising a step of providing the side walls (15) of the filaments (11) with resistive barriers (25), and a coating step, in which the filaments (11) are embedded in a conductive coating material that forms a coating (30) of the tape (1).

13. (Original) The method according to Claim 12, characterized by comprising an etching step, in which a plurality of grooves (14) is dug through the superconductive material layer (5) throughout the whole thickness of said superconductive material layer (5) in order to delimit the filaments (11); said resistive barriers (25) being formed in said etching step, by modifying the structure of the superconductive material of said side walls (15).

14. (Original) The method according to Claim 13, characterized in that, in the etching step, the grooves (14) are dug in discontinuous stretches, in such a way that each groove (14) is interrupted by transverse bridges (17) connecting adjacent filaments.

15. (Currently Amended) The method according to Claim 13 ~~or Claim 14~~, characterized in that, in the etching step, the tape (1) is dug up to the substrate (2).

16. (Currently Amended) The method according to ~~any one of Claims 13 to 15~~, characterized in that the tape (1) comprises at least one buffer layer (4) set between the substrate (2) and the superconductive material layer (5), and the etching step is carried out through the superconductive material layer (5) and through the buffer layer (4) up to the substrate (2).

17. (Currently Amended) The method according to ~~any one of Claims 12 to 16~~, characterized in that the coating material is a metal material.

18. (Currently Amended) The method according to ~~any one of Claims 12 to 17~~, characterized in that, in said coating step, the coating material fills said grooves (14) and coats said filaments (11).

19. (Currently Amended) The method according to ~~any one of Claims 12 to 18~~, characterized in that it comprises a step of winding the tape (1) on itself about said axis (A) to form a thread (33) in which the filaments (11) are substantially parallel to said axis (A).

20. (Currently Amended) The method according to ~~any one of Claims 12 to 19~~,

characterized in that it comprises a step of twisting the tape (1) on itself along said axis (A) to form a tress-like thread (33) in which said filaments (11) are substantially spirally wound with respect to one another.

21. (Currently Amended) The method according to ~~any one of Claims 12 to 20,~~
characterized in that it comprises a step of connecting the filaments (11) to one another via
transverse bridges (17) made of superconductive material.